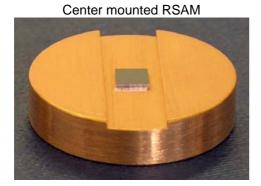


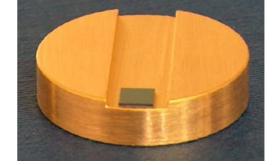
## Soldered RSAM data sheet RSAM- $\lambda$ -25.0s

GaAs chip area	standard: optional:	4mm x 4mm other dimensions on request
Chip thickness	standard:	400 µm
Front side	the RSAM is covered by a dielectric front mirror.	

The RSAM chip is soldered on a gold plated Cu-cylinder with 25.0 mm Ø using a Pb/Sn solder. The solder provides a low thermal resistance between the RSAM and the mount.

- The *standard* position of the RSAM is at the center of the mount.
- **Optional** the RSAM can be mounted at the edge of the mount without extra charges.





Edge mounted RSAM

## Mount Cu-cylinder, ∅ = 25.0 mm I = 6.0 mm

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